



## Material Content Data Sheet



Sales Product Name	BGS 12SL6 E6327			Issued		27. February 2015		
MA#	MA001034800							
Package	PG-TSLP-6-4			Weight*		0.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.141	18.37	18.37	183653	183653
bumps	non noble metal	copper	7440-50-8	0.033	4.32	4.32	43215	43215
leadframe	non noble metal	nickel	7440-02-0	0.173	22.49	22.49	224938	224938
encapsulation	organic material	carbon black	1333-86-4	0.002	0.25		2533	
	plastics	epoxy resin	-	0.057	7.35		73453	
	inorganic material	silicondioxide	60676-86-0	0.332	43.06	50.66	430590	506576
leadfinish	noble metal	gold	7440-57-5	0.009	1.20	1.20	12019	12019
plating	noble metal	silver	7440-22-4	0.015	1.96	1.96	19627	19627
ubm	non noble metal	copper	7440-50-8	0.000	0.02		161	
	non noble metal	titanium	7440-32-6	0.000	0.01		57	
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.03	30	248
solder	noble metal	silver	7440-22-4	0.000	0.02		223	
	non noble metal	tin	7440-31-5	0.007	0.95	0.97	9501	9724
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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